Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1415	257/734.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:25
L2	819	257/675.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:26
L3	1376	257/706.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:27
L4	1025	257/717.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:27
S1	1	((heat adj (sink or spreader)) with ((low adj expansion) with material)) and ((silicon adj carb$3) or SiC) and (aluminum or AL)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 11:38
S2	7	("5025347" | "5844310" | "5981085" | "6129993" | "6132676" | "6381094" | "6597574").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/19 19:29
S3	4	((heat adj (sink or spreader)) with ((low adj expansion) with material)) and ((silicon adj carb$3) or SiC) and (aluminum or AL)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 19:41
S4	3533	((heat adj (sink or spreader)) and ((silicon adj carb$3) or SiC) and (aluminum or AL))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 15:45
S5	2	"6753093"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 15:30
S6	7	("5025347" | "5844310" | "5981085" | "6129993" | "6132676" | "6381094" | "6597574").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/15 15:30

S7	319	S4 and ((heat adj (sink or spreader)) with (((silicon adj carb$3) or SiC) and (aluminum or AL)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 15:46
S8	95	S7 and (circuit adj board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:32
S9	25	S8 and (stress with (reduc$4 or relie$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:12
S10	2	("6318442").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:34
S11	7	S8 and (auto or automobile)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:38
S12	872	S4 and (circuit adj board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:39
S13	420	S12 and ((circuit adj board) with heat)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:39
S14	292	S13 and (heat with (chip or semiconductor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:40
S15	172	S14 and stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:19
S16	16	S15 and tobita.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:18

S17	0	S16 and (low adj expansion) .	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:19
S18	0	S16 and (low with expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:19
S19	93	S14 and (low with expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:19
S20	74	S19 and stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:19
S21	19	("5006417").URPN.	USPAT	OR	ON	2005/09/15 17:24
S22	28	((heat adj (sink or spreader)) with ((low with expansion) with material)) and ((silicon adj carb$3) or SiC) and (aluminum or AL)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 11:39
S23	61	((heat adj (sink or spreader)) with ((low with expansion) with material)) and ((heat adj (sink or spreader)) with (between and (chip or (semiconductor adj element))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 11:43
S24	31	S23 and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 11:43
S25	23	S24 and (metal with substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:21